



TLV3491 TLV3492 TLV3494

SBOS262C - DECEMBER 2002 - REVISED MAY 2004

1.8V, Nanopower, PUSH-PULL OUTPUT COMPARATOR

FEATURES

- VERY LOW SUPPLY CURRENT: 0.8µA (typ)
- INPUT COMMON-MODE RANGE 200mV BEYOND SUPPLY RAILS
- SUPPLY VOLTAGE: +1.8V to +5.5V
- HIGH SPEED: 6us
- PUSH-PULL CMOS OUTPUT STAGE
- SMALL PACKAGES: SOT23-5 (Single) SOT23-8 (Dual)

APPLICATIONS

- PORTABLE MEDICAL EQUIPMENT
- WIRELESS SECURITY SYSTEMS
- REMOTE CONTROL SYSTEMS
- HANDHELD INSTRUMENTS
- ULTRA-LOW POWER SYSTEMS

DESCRIPTION

The TLV349x family of push-pull output comparators features a fast $6\mu s$ response time and $< 1.2\mu A$ (max) nanopower capability, allowing operation from 1.8V - 5.5V. Input common-mode range beyond supply rails make the TLV349x an ideal choice for low-voltage applications.

Micro-sized packages provide options for portable and spacerestricted applications. The single (TLV3491) is available in SOT23-5 and SO-8. The dual (TLV3492) comes in SOT23-8 and SO-8. The quad (TLV3494) is available in TSSOP-14 and SO-14.

The TLV349x is excellent for power-sensitive, low-voltage (2-cell) applications.

TLV349x RELATED PRODUCTS

PRODUCT	FEATURES
TLV370x	560nA, 2.5V to 16V, Push-Pull CMOS Output Stage Comparator
TLV340x	550nA, 2.5V to 16V, Open Drain Output Stage Comparator



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ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage	+5.5V
Signal Input Terminals, Voltage ⁽²⁾	(V-) - 0.5V to (V+) + 0.5V
Current ⁽²⁾	±10mA
Output Short-Circuit ⁽³⁾	Continuous
Operating Temperature	40°C to +125°C
Storage Temperature	65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
ESD Rating (Human Body Model)	3000V

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied. (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less. (3) Short-circuit to ground, one amplifier per package.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

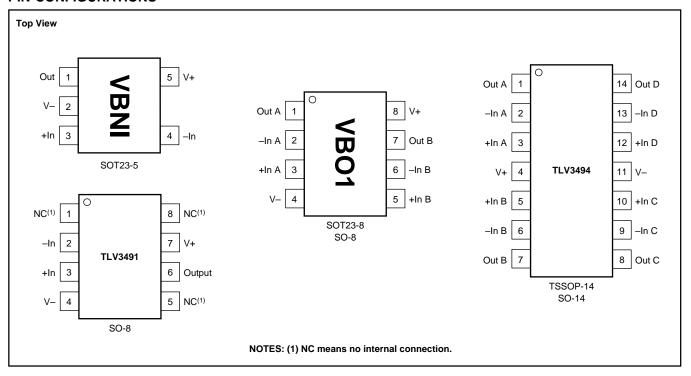
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION(1)

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
TLV3491	SOT23-5	DBV "	–40°C to +125°C "	VBNI "	TLV3491AIDBVT TLV3491AIDBVR	Tube, 250 Tape and Reel, 3000
TLV3491	SO-8	D "	-40°C to +125°C	TLV3491 "	TLV3491AID TLV3491AIDR	Tube, 100 Tube, 2500
TLV3492	SOT23-8	DCN "	-40°C to +125°C	VBO1	TLV3492AIDCNT TLV3492AIDCNR	Tube, 250 Tape and Reel, 3000
TLV3492	SO-8	D "	–40°C to +125°C "	TLV3492 "	TLV3492AID TLV3492AIDR	Tube, 100 Tape and Reel, 2500
TLV3494	TSSOP-14	PW "	-40°C to +125°C	TLV3494 "	TLV3494AIPWT TLV3494AIPWR	Tape and Reel, 94 Tape and Reel, 2500
TLV3494 "	SO-14 "	D "	-40°C to +125°C	TLV3494 "	TLV3494AID TLV3494AIDR	Tape and Reel, 58 Tape and Reel, 2500

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.

PIN CONFIGURATIONS



ELECTRICAL CHARACTERISTICS: $V_S = +1.8V$ to +5.5V

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+125^{\circ}C$.

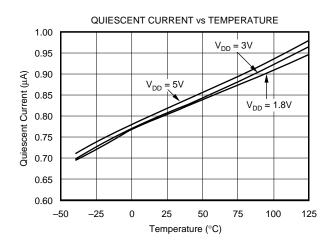
At T_A = +25°C, and V_S = +1.8V to +5.5V, unless otherwise noted.

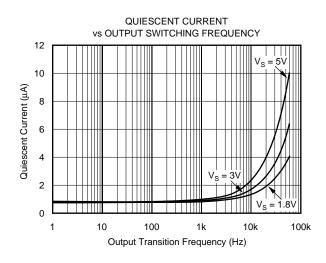
			TLV3491, TLV3492, TLV3494			
PARAMETER		CONDITION	MIN	TYP	MAX	UNITS
OFFSET VOLTAGE Input Offset Voltage vs Temperature vs Power Supply	V _{OS} dV _{OS} /dT PSRR	$V_{CM} = 0V, I_{O} = 0V$ $T_{A} = -40^{\circ}C \text{ to } +125^{\circ}C$ $V_{S} = 1.8V \text{ to } 5.5V$		±3 ± 12 350	±15	mV μ V/°C μV/V
INPUT BIAS CURRENT Input Bias Current Input Offset Current	I _B I _{OS}	$V_{CM} = V_{CC}/2$ $V_{CM} = V_{CC}/2$		±1 ±1	±10 ±10	pA pA
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection Ratio	V _{CM} CMRR	$V_{CM} = -0.2V \text{ to } (V+) - 1.5V$ $V_{CM} = -0.2V \text{ to } (V+) + 0.2V$	(V-) - 0.2V 60 54	74 62	(V+) + 0.2V	V dB dB
INPUT CAPACITANCE Common-Mode Differential				2 4		pF pF
SWITCHING CHARACTERISTICS Propagation Delay Time, Low-to-High Propagation Delay Time, High-to-Low Rise Time	t _(PHL)	$f = 10 kHz, V_{STEP} = 1V$ Input Overdrive = 10mV Input Overdrive = 100mV Input Overdrive = 10mV Input Overdrive = 100mV $C_L = 10 pF$		12 6 13.5 6.5 100		μs μs μs μs ns
Fall Time OUTPUT Voltage Output High from Rail Voltage Output Low from Rail Short-Circuit Current	V _{OH} V _{OL} I _{SC}	$C_L = 10pF$ $V_S = 5V$ $I_{OUT} = 5mA$ $I_{OUT} = 5mA$	See	90 160 Typical Characteris	200 200 stics	mV mV
POWER SUPPLY Specified Voltage Operating Voltage Range Quiescent Current(1)	V _S	V _O = 5V, V _O = High	1.8 1.8	0.85	5.5 5.5 1.2	V V μΑ
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance, $θ$ _{JA} SOT23-5, SOT23-8 SO-8 SO-14, TSSOP-14			-40 -40 -65	200 150 100	+125 +125 +150	°C °C °C/W °C/W °C/W

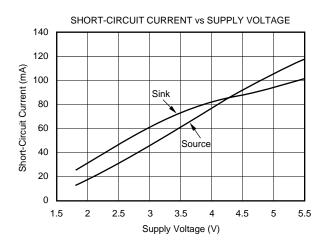
NOTE: (1) I_Q per channel.

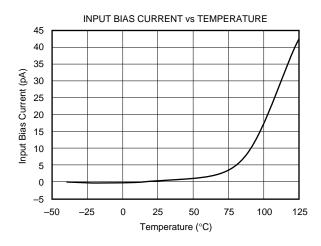
TYPICAL CHARACTERISTICS

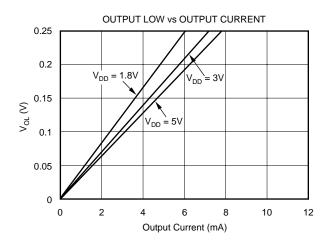
At $T_A = +25$ °C, $V_S = +1.8$ V to +5.5V, and Input Overdrive = 100mV, unless otherwise noted.

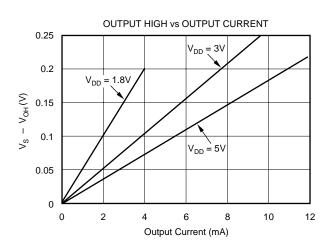






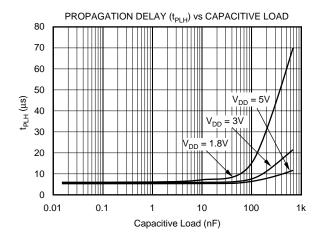


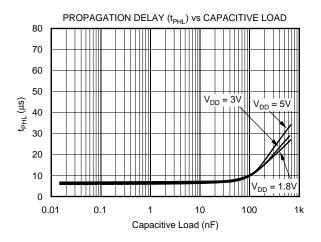


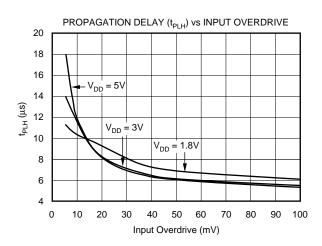


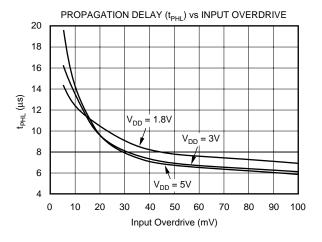
TYPICAL CHARACTERISTICS (Cont.)

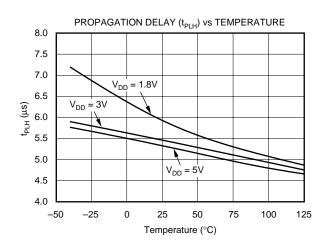
At $T_A = +25$ °C, $V_S = +1.8$ V to +5.5V, and Input Overdrive = 100mV, unless otherwise noted.

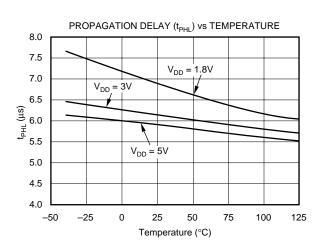






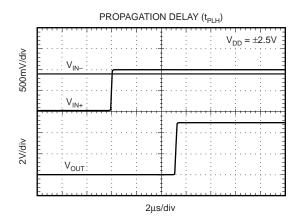


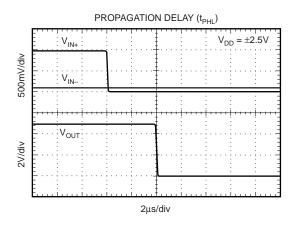


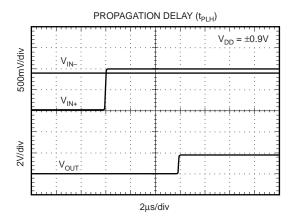


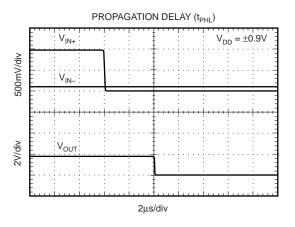
TYPICAL CHARACTERISTICS (Cont.)

At $T_A = +25$ °C, $V_S = +1.8$ V to +5.5V, and Input Overdrive = 100mV, unless otherwise noted.









APPLICATIONS INFORMATION

The TLV349x family of comparators features rail-to-rail input and output on supply voltages as low as 1.8V. The push-pull output stage is optimal for reduced power budget applications and features no shoot-through current. Low supply voltages, common-mode input range beyond supply rails, and a typical supply current of 0.8µA make the TLV349x family an excellent candidate for battery-powered applications with single-cell operation.

BOARD LAYOUT

Figure 1 shows the typical connections for the TLV349x. To minimize supply noise, power supplies should be capacitively decoupled by a $0.01\mu F$ ceramic capacitor in parallel with a $10\mu F$ electrolytic capacitor. Comparators are very sensitive to input noise. Proper grounding (use of ground plane) and guarding of high-impedance nodes will help maintain specified performance of the TLV349x family.

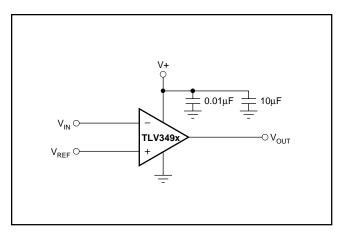


FIGURE 1. Basic Connections of the TLV349x.

SETTING REFERENCE VOLTAGE

It is important to use a stable reference when setting the transition point for the TLV349. The REF1004 provides a 1.25V reference voltage with low drift and only $8\mu A$ of quiescent current.

EXTERNAL HYSTERESIS

Comparator inputs have no noise immunity within the range of specified offset voltage ($\pm 15 \text{mV}$). For noisy input signals, the comparator output may display multiple switching as input signals move through the switching threshold. The typical comparator threshold of the TLV349x is $\pm 15 \text{mV}$. To prevent multiple switching within the comparator threshold of the TLV349x, external hysteresis may be added by connecting a small amount of feedback to the positive input. Figure 2 shows a typical topology used to introduce hysteresis, described by the equation:

$$V_{HYST} = \frac{V^+ \times R_1}{R_1 + R_2}$$

V_{HYST} will set the value of the transition voltage required to switch the comparator output by increasing the threshold region, thereby reducing sensitivity to noise.

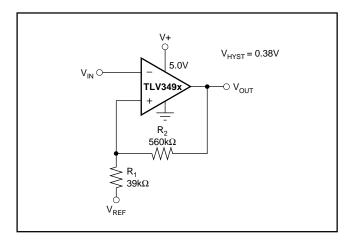


FIGURE 2. Adding Hysteresis to the TLV349x.

APPLICATIONS

RELAXATION OSCILLATOR

The TLV349x can be configured as a relaxation oscillator to provide a simple and inexpensive clock output (see Figure 3.) The capacitor is charged at a rate of 0.69RC. It also discharges at a rate of 0.69RC. Therefore, the period is 1.38RC. R_1 may be a different value than R_2 .

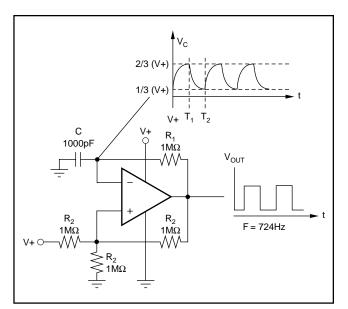


FIGURE 3. TLV349x Configured as a Relaxation Oscillator.

POWER-ON RESET

The reset circuit shown in Figure 4 provides a time delayed release of reset to the MSP430 microcontroller. Operation of the circuit is based on a stabilization time constant of the supply voltage, rather than on a predetermined voltage value. The negative input is a reference voltage created by

a simple resistor divider. These resistor values should be relatively high to reduce the current consumption of the circuit. The positive input is an RC circuit that provides a power-up delay. When power is applied, the output of the comparator is low, holding the processor in the reset condition. Only after allowing time for the supply voltage to stabilize does the positive input of the comparator become higher than the negative input, resulting in a high output state, and releasing the processor for operation. The stabilization time required for the supply voltage is adjustable by the selection of the RC component values. Use of a lowervalued resistor in this portion of the circuit will not increase current consumption because no current flows through the RC circuit after the supply has stabilized. The reset delay time needed depends on the power-up characteristics of the system power supply. R₁ and C₁ are selected to allow enough time for the power supply to stabilize. D1 provides rapid reset if power is lost. In this example, the $R_1 \cdot C_1$ time constant is 10mS.

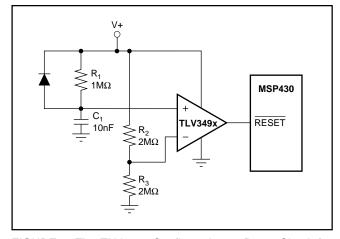


FIGURE 4. The TLV349x Configured as a Reset Circuit for the MSP430.





19-May-2004

PACKAGING INFORMATION

ORDERABLE DEVICE	STATUS(1)	PACKAGE TYPE	PACKAGE DRAWING	PINS	PACKAGE QTY
TLV3491AID	ACTIVE	SOIC	D	8	100
TLV3491AIDBVR	ACTIVE	SOP	DBV	5	3000
TLV3491AIDBVT	ACTIVE	SOP	DBV	5	250
TLV3491AIDR	ACTIVE	SOIC	D	8	2500
TLV3492AID	ACTIVE	SOIC	D	8	100
TLV3492AIDCNR	ACTIVE	SSOP	DCN	8	3000
TLV3492AIDCNT	ACTIVE	SSOP	DCN	8	250
TLV3492AIDR	ACTIVE	SOIC	D	8	2500
TLV3494AID	ACTIVE	SOIC	D	14	58
TLV3494AIDR	ACTIVE	SOIC	D	14	2500
TLV3494AIPWR	ACTIVE	TSSOP	PW	14	2500
TLV3494AIPWT	ACTIVE	TSSOP	PW	14	250

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs. **LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

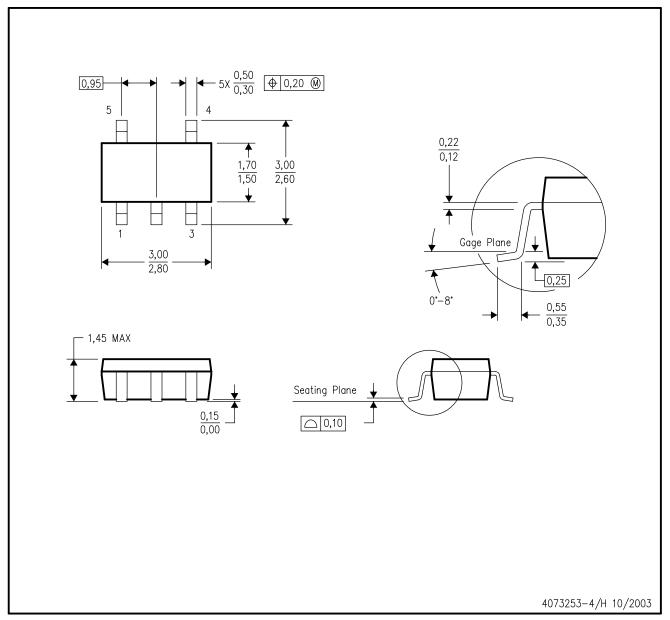
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



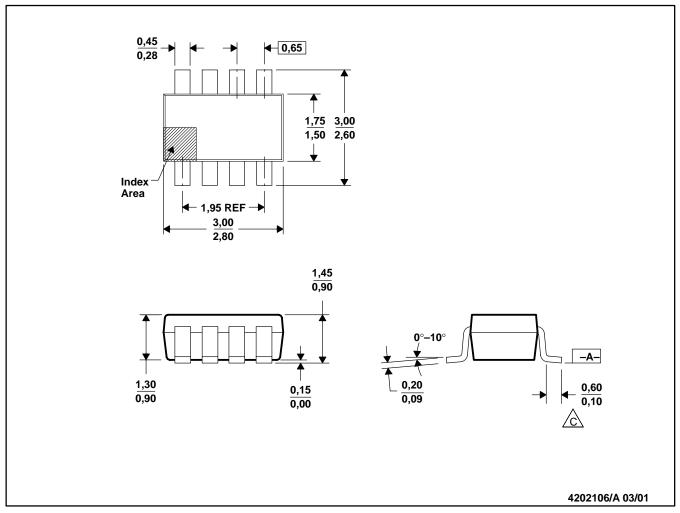
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- C. Body dimensions do not include mold fla D. Falls within JEDEC MO—178 Variation AA. Body dimensions do not include mold flash or protrusion.



DCN (R-PDSO-G8)

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

Foot length measured reference to flat foot surface parallel to Datum A.

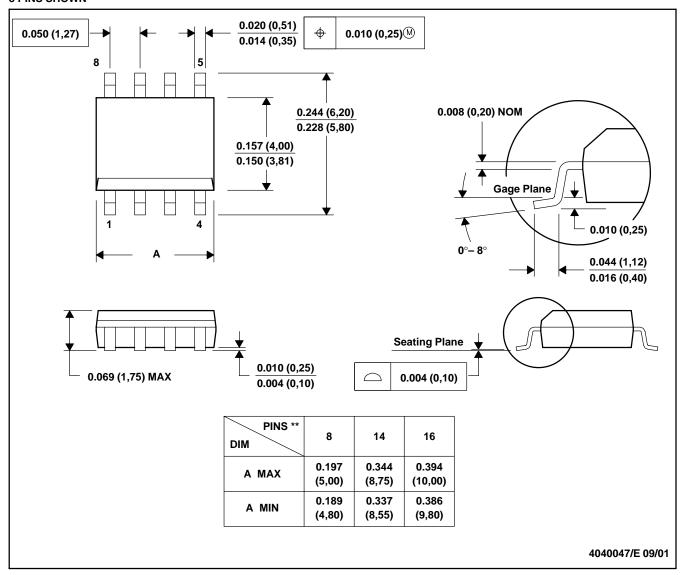
- D. Package outline exclusive of mold flash, metal burr and dambar protrusion/intrusion.
- E. Package outline inclusive of solder plating.
- F. A visual index feature must be located within the cross-hatched area.



D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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